



- Faster and increased solder absorption
- Wound on static dissipative spools
- PCBs will meet MIL-P-28809A Cleanliness Test without cleaning
- Negligible residues which are non-corrosive, clear and non-hygroscopic
- Heat stable coating
- Vacuum packed
- **Excellent shelf life**
- New size No Clean Microwick (NC-MW) for SMD replacement



DESCRIPTION

A new No Clean Desoldering Wick designed for static-free desoldering and repair of PC boards without the need for subsequent cleaning.

Multicore No Clean Wick uses a special halide-free vacuumised no-clean, flux-coated copper braid designed to improve wicking. It will not lose its efficiency even after prolonged storage in humid conditions. The wick remains flexible and will not flake. PC boards meet MIL-P-28809A Cleanliness Test without cleaning.

Multicore No Clean Wick is available in five sizes, including a Microwick size (NC-MW) for SMD replacement. Each size has colour coded packaging for easy identification and is supplied on 1.5m or 3m static dissipative spools meeting DOD standards.

APPLICATION

Lay Multicore No Clean Wick over the solder requiring removal and place the soldering iron tip on top of the copper braid. The braid and solder beneath will gradually heat until the solder melts and is absorbed into the braid by capillary action. Remove the braid, cut off the solder-filled length and dispose of lead contaminated copper properly.

Sudden heat shock, which may be produced when using a preheated vaccum desoldering tool, is prevented since the braid is cold when it first comes into contact with the joint to be desoldered.

SPECIAL PROPERTIES

Multicore No Clean Wick is supplied on static dissipative spools conforming to both (DOD) Standard 1686 and DOD Handbook 263 for static discharge protection and meets the decay rate provision of MIL-B-81705B.

Specially processed copper braid is coated with a reduced volume of time tested Xersin 2005 halide free synthetic resin, so that the quantity of residue after use is significantly less than with conventional desoldering wick. Xersin 2005 meets Bellcore TR-TSY 000078 issue 2, ANSI/IPC SF-818 and is rated IPC-LR3CN.

PCBs will pass the MIL-P-28809A Cleanliness Test without cleaning, provided a No Clean flux and a clean system and components are used. PCBs will also pass this test if they have been cleaned after the soldering operation, provided they have been reworked using a No Clean flux in a clean environment.

PACKAGING

Multicore No Clean Wick is supplied in static dissipative plastic spools of 1.5m (5 ft) each. This provides convenient application and protects the user from heat.

Packaged ten static dissipative spools per vacuum packed sleeve and five sleeves per box for a total of fifty spools per carton. Also available in 100 ft Econo-spools.

Size Reference	Approximate Width	Label Colour Code
NC-MW	0.5mm (0.02in)	Orange
NC-00	0.8mm (0.03in)	White
NC-AA	1.5mm (0.06in)	Yellow
NC-AB	2.2mm (0.08in)	Green
NC-BB	2.7mm (0.10in)	Blue

SHELF LIFE

Due to the nature of the Xersin 2005 flux coating, Multicore No Clean Wick does not lose its efficiency even after prolonged storage in humid conditions, whereas conventional rosin coated wicks may lose their efficiency under such conditions.

HEALTH AND SAFETY

WARNING: The following information is for guidance only and users must refer to the Material Safety Data Sheet relevant to Multicore No Clean Desoldering Wick before use.

Fume Hazards and Precautions: The fumes evolved during use may irritate the nose and respiratory organs of some sensitive subjects. Avoid excessive inhalation of the fumes. Suitable fume extraction equipment should be used to extract fumes away from the operators. When used at normal soldering temperatures the amount of lead fume given off is negligible.

Protection and Hygiene: Eating, drinking and smoking should not be permitted in the working area. Hands should be washed with soap and warm water after handling this product, especially before eating.

Waste Disposal: Waste material should be disposed of in accordance with local regulations.

Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, Loctite Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Loctite Corporation's products. Loctite Corporation specifically Corporation's products. disclaims any liability for consequential or incidental damages of any kind, including lost profits. The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Loctite Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.



Loctite Electronics

Henkel Loctite UK Ltd, Watchmead, Welwyn Garden City, Hertfordshire, AL7 1JB, England UK.: 01707 358800

Loctite is a Trademark of Henkel Loctite Corp. U.S.A

www.loctite.com

